



## 特点

- \* 外形尺寸: 86.0 × 62.0 × 12.7 mm
- \* 工业标准封装和引脚
- \* 高效率、高功率密度
- \* 基板工作温度 85℃

## **Features**

- \* Size:  $3.39 \times 2.44 \times 0.50$  inch
- \* Industry Standard Package and Footprint
- \* High Efficiency, High Power Density
- \* 85℃ Baseplate Operation

输入特性(Input)			注释(Notes and Conditions)
输入电压范围(Input Voltage Range)		36~72Vdc	80Vdc Max
遥控功能(Remote On/Off Function)			
负逻辑(Negative Logic)	开启(On)	与-Vin 短接(Connect to -Vin)	相对于 -Vin (Reference to -Vin)
	关闭(Off)	悬空(Open Circuit)	

输出特性(Output)		注释(Notes and Conditions)
输出电压精度(Voltage Set-Point Accuracy)	± 1%	Vinom and Ionom
输出电压调节范围(Output Voltage Trim Range)	± 10%	
源效应(Line Regulation)	± 0.4%Vo	Vimin~Vimax, Ionom
负载效应(Load Regulation)	± 0.8%Vo	10%~100%lonom, Vinom
输出过流保护点(Current Limit Threshold Range)	110%~140%lo	
短路保护(Short-Circuit Protection)	连续可恢复	
	(Continuous, Automatic Recovery)	
瞬态响应(Dynamic Response)		
过冲幅度(Peak Deviation)	± 5%Vo	25%-50%-25% of Ionom
恢复时间(Settling Time)	200 μ s	and 50%-75%-50% of lonom

一般特性(General)		注释(Notes and Conditions)
温度系数(Temperature Coefficient)	± 0.02%/℃	
隔离电压(Isolation Voltage)		
输入与输出(Input-Output)	1000Vdc 1min	
输入与外壳(Input-Case)	750Vdc 1min	
输出与外壳(Output-Case)	500Vdc 1min	
工作基板温度(Operating Baseplate Temperature)	- 20℃~ + 85℃	
贮存温度(Storage Temperature)	- 40℃~ + 105℃	
冷却方式(Cooling)	加装散热器或强制风冷	Attach Heatsink or Forced Convection
过温保护(Thermal Shutdown Range)	+100℃~+110℃	基板温度(Baseplate Temperature)
平均故障间隔时间(MTBF)	2 × 10 <sup>5</sup> h	MIL-HDBK-217
重量(Weight)	120g	

注:除非另有说明,指标一般在标称输入电压、满载和25℃基板温度下测得。

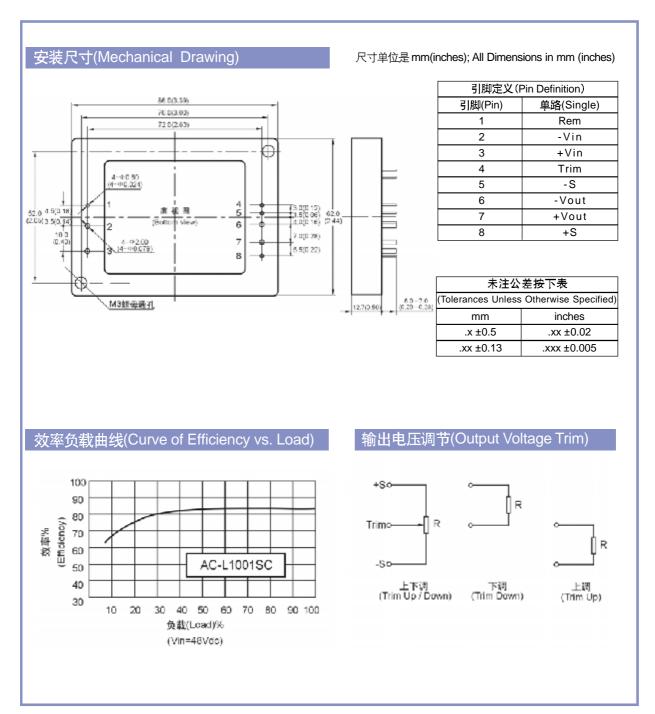
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## 型号列表(Models)

产品型号	标称输入电压	标称输出电压	标称负载	额定输出功率	效率	输出杂音电压峰峰值
(Model Number)	(Input Voltage)	(Output Voltage)	(Output Current)	(Output Power)	(Efficiency)	(Ripple and Noise)
	Vdc	Vdc	Α	W	%	mVp-p
AC-L1001SC	48	5.0	20.0	100.0	83	100
AC-L1002SC	48	12.0	8.4	100.8	86	100

注: "-L" 型号遥控功能为负逻辑。(Model with "-L" is Negative Logic.)



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